

Electronic Patent Application Fee Transmittal

Application Number:	10537959			
Filing Date:	07-Jun-2005			
Title of Invention:	Thermoplastic polyimide resin film, multilayer body and method for manufacturing printed wiring board composed of same			
First Named Inventor/Applicant Name:	Shigeru Tanaka			
Filer:	Darius G. Adli/Yaning Liu			
Attorney Docket Number:	81844.0036			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 3 months with \$0 paid	1253	1	1110	1110

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				1110